

Features

- Green Device Available
- Super Low Gate Charge
- ESD Protection
- Excellent CdV/dt effect decline
- Advanced high cell density Trench

Product Summary

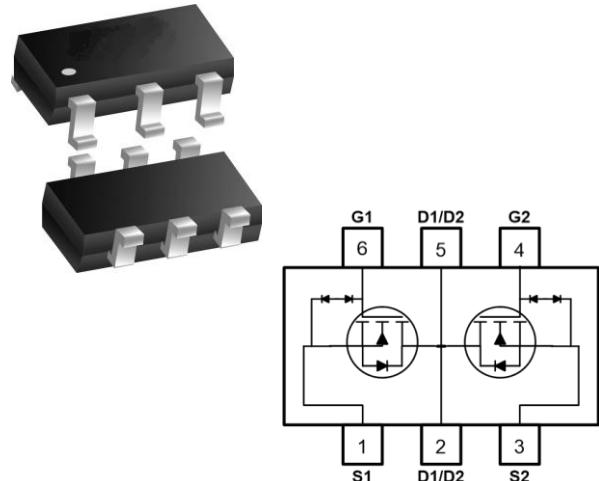
BVDSS	RDS(ON)	ID
20V	17mΩ	7A

Description

The JHT62724 is the high cell density trenched N-ch MOSFETs, which provides excellent RDS(ON) and efficiency for most of the small power switching and load switch applications.

The JHT62724 meet the RoHS and Green Product requirement with full function reliability approved.

SOT-23-6 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	20	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _A =25°C	Continuous Drain Current ¹	7.0	A
I _D @T _A =70°C	Continuous Drain Current ¹	5.6	A
I _{DM}	Pulsed Drain Current ²	45	A
P _D @T _A =25°C	Total Power Dissipation ³	1.25	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	100	°C/W

N-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	20	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=4.5\text{V}$, $I_D=3.5\text{A}$	12	14	17	$\text{m}\Omega$
		$V_{\text{GS}}=4.0\text{V}$, $I_D=3.5\text{A}$	12.5	14.5	17.5	
		$V_{\text{GS}}=3.7\text{V}$, $I_D=3.5\text{A}$	13	15	18	
		$V_{\text{GS}}=3.1\text{V}$, $I_D=3.5\text{A}$	14	16	20	
		$V_{\text{GS}}=2.5\text{V}$, $I_D=3.5\text{A}$	16	19.5	24.5	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	0.5	0.7	1.2	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^{\circ}\text{C}$	---	---	1	uA
		$V_{\text{DS}}=16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 8\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 10	uA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_D=3.5\text{A}$	---	20	---	S
Q_g	Total Gate Charge	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=7\text{A}$	---	11	---	nC
Q_{gs}	Gate-Source Charge		---	1.2	---	
Q_{gd}	Gate-Drain Charge		---	3.2	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $R_G=3.3\Omega$	---	52	---	ns
T_r	Rise Time		---	302	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	805	---	
T_f	Fall Time		---	662	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	523	---	pF
C_{oss}	Output Capacitance		---	81	---	
C_{rss}	Reverse Transfer Capacitance		---	56	---	
Diode Characteristics						
I_s	Continuous Source Current ^{1,4}	$V_G=V_D=0\text{V}$, Force Current	---	---	7	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^{\circ}\text{C}$	---	0.78	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, $t \leq 10\text{s}$.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

N-Channel Typical Characteristics

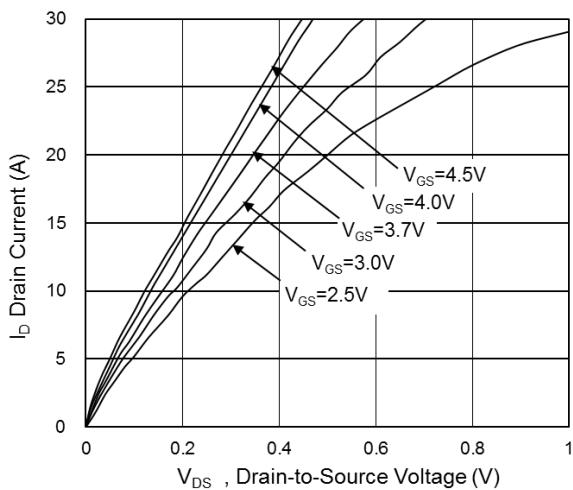


Fig.1 Typical Output Characteristics

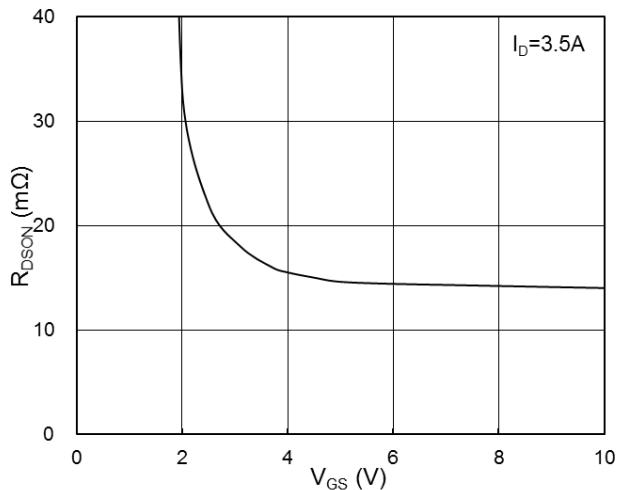


Fig.2 On-Resistance vs. G-S voltage

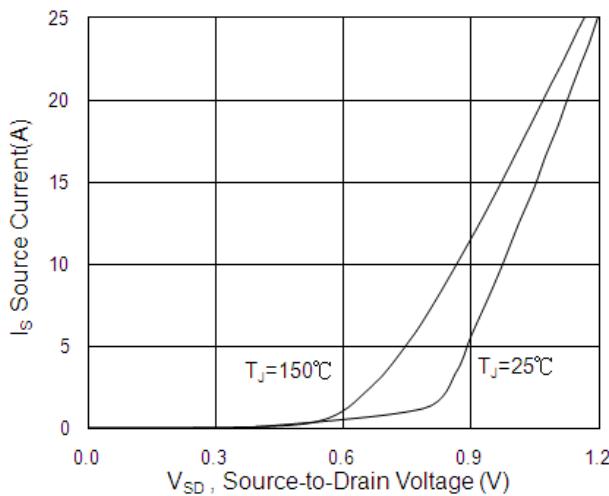


Fig.3 Source-Drain Forward Characteristics

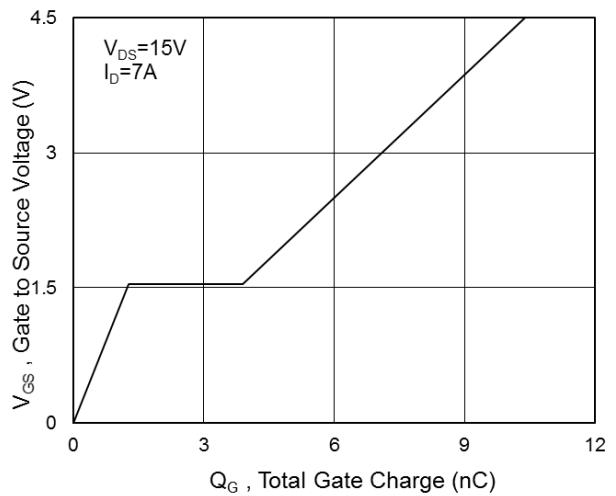


Fig.4 Gate-Charge Characteristics

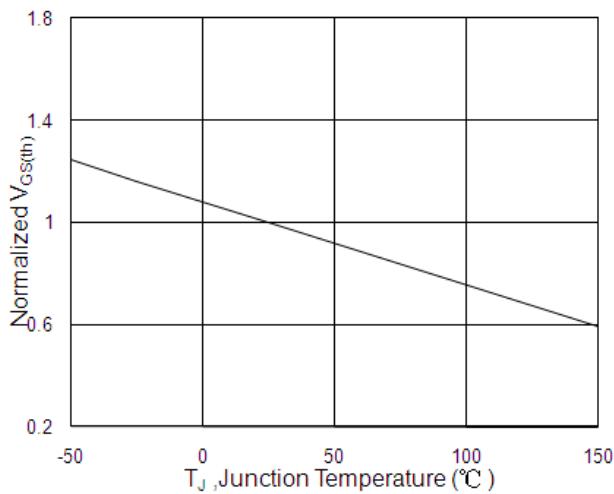


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

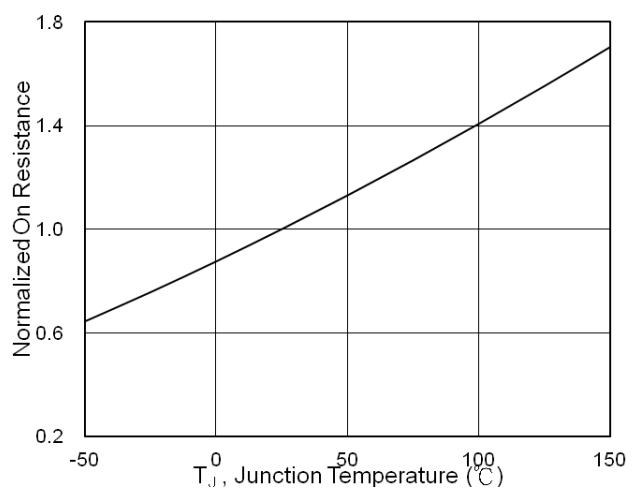


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

JHT62724

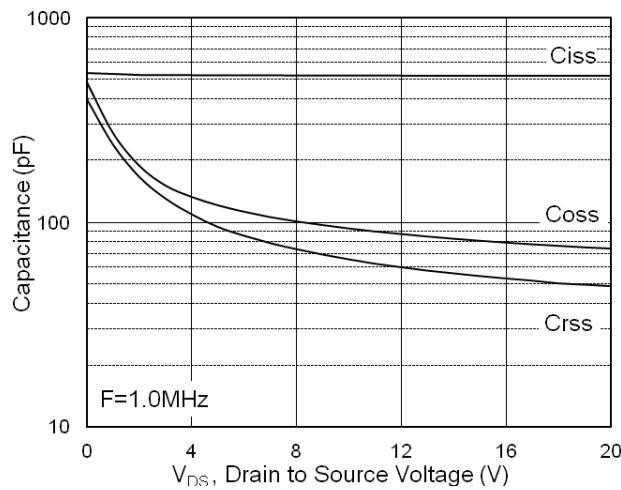


Fig.7 Capacitance

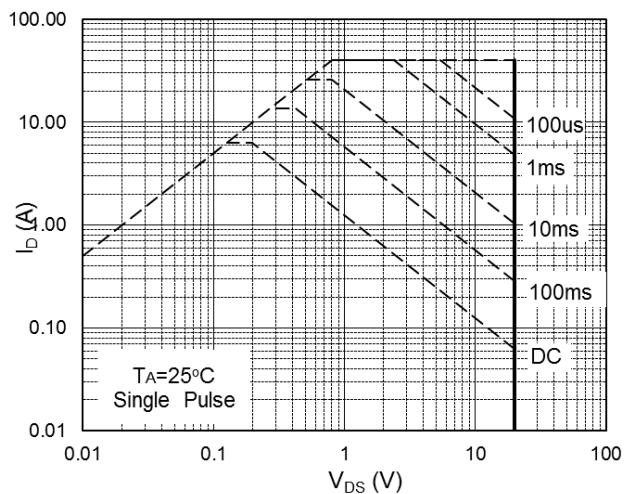


Fig.8 Safe Operating Area

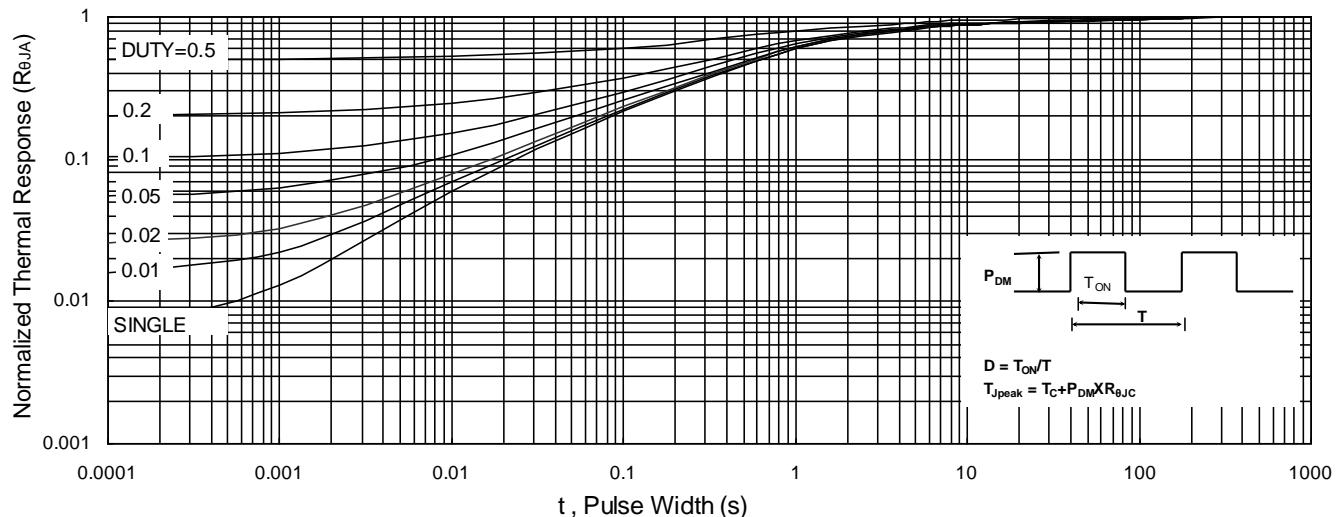


Fig.9 Normalized Maximum Transient Thermal Impedance

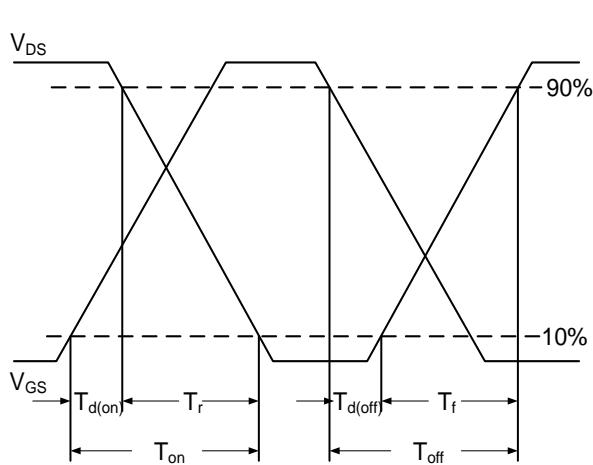


Fig.10 Switching Time Waveform

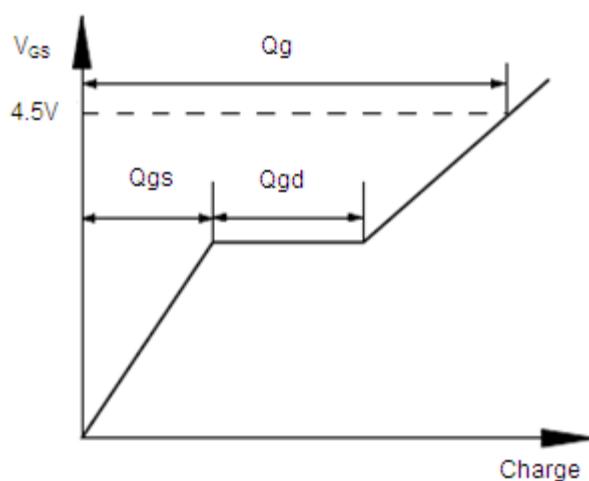
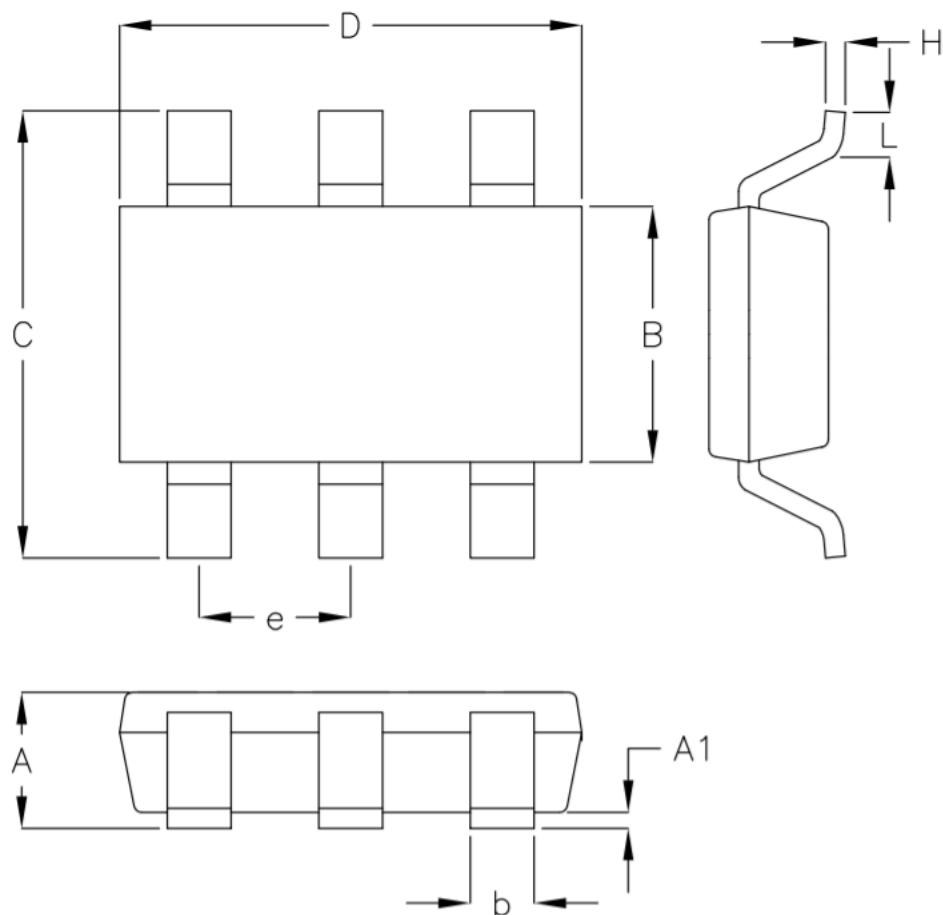


Fig.11 Gate Charge Waveform

SOT-23-6 Package Outline



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.90	0.028	0.035
A1	0.00	0.10	0.000	0.004
B	1.50	1.70	0.059	0.067
b	0.35	0.50	0.014	0.020
C	2.60	3.00	0.102	0.119
D	2.80	3.02	0.110	0.119
e	0.90	1.00	0.035	0.039
H	0.08	0.20	0.003	0.008
L	0.30	0.60	0.012	0.024

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